

/ Descriptions

TO-277
TO-277 Plastic package Schottky diode.

/ Features

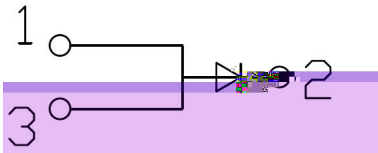
$$V_F(\text{typ})=0.35\text{V}$$

High Forward Surge Capability, Ultra Low Forward Voltage Drop $V_F(\text{typ})=0.36\text{V}$, Excellent High Temperature Stability. HF Product.

/ Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

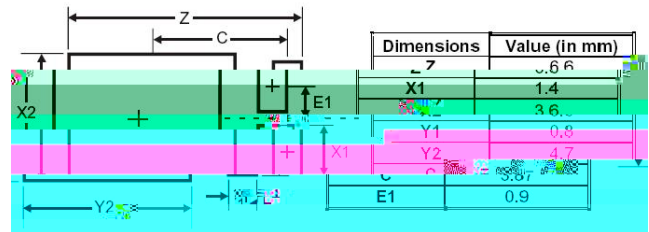
/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode



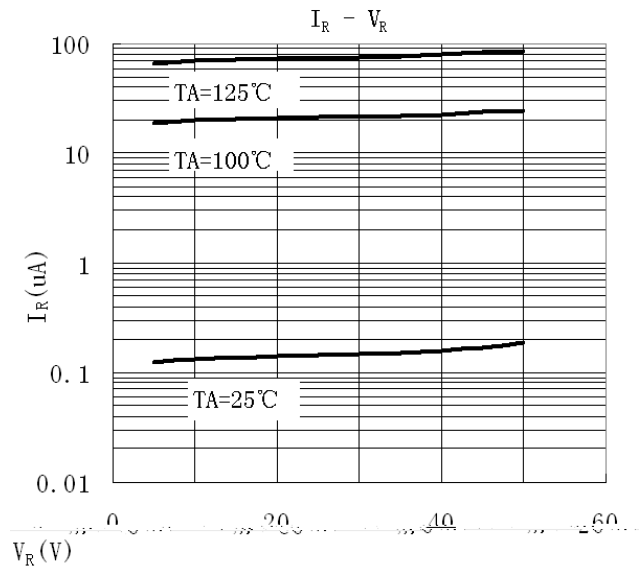
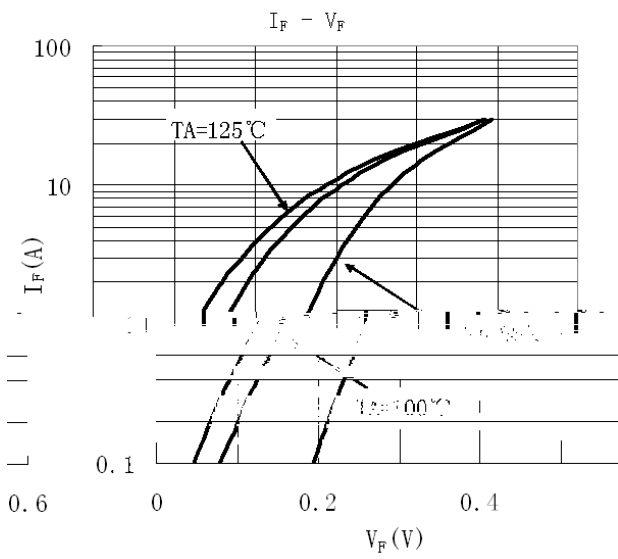
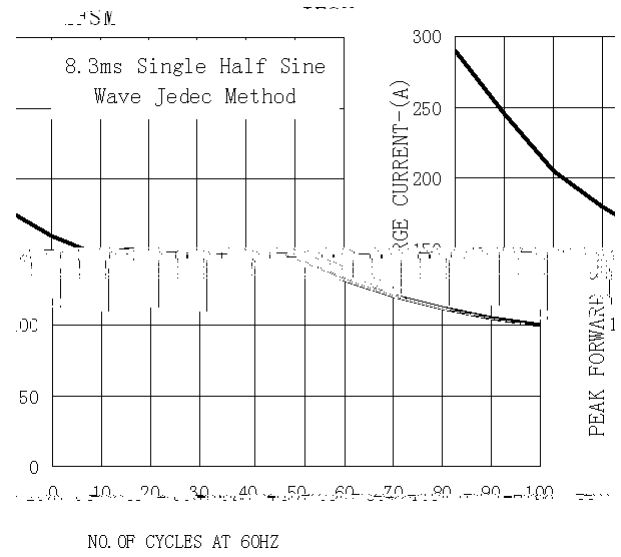
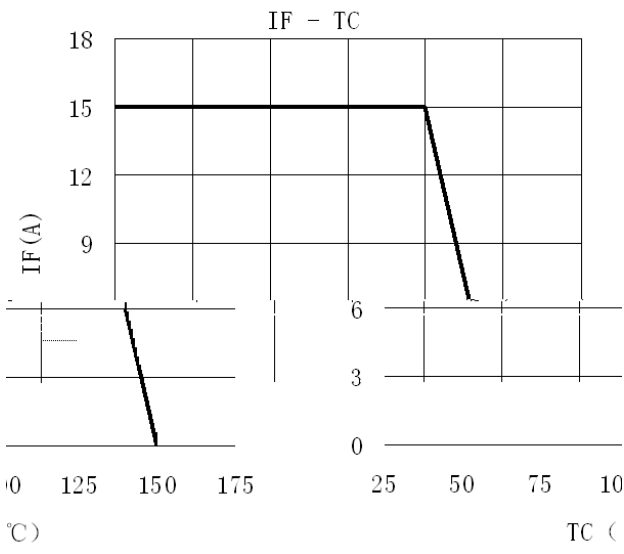
Suggested Pad layout

/ h_{FE} Classifications & Marking

See Marking Instructions.

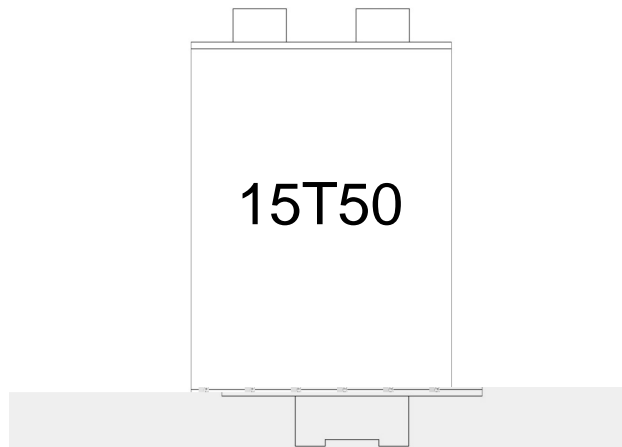
LV15T50E
Rev.G Sep.-2018

/ Electrical Characteristic Curve



LV15T50E
Rev.G Sep.-2018

/ Marking Instructions



15T50

Note:

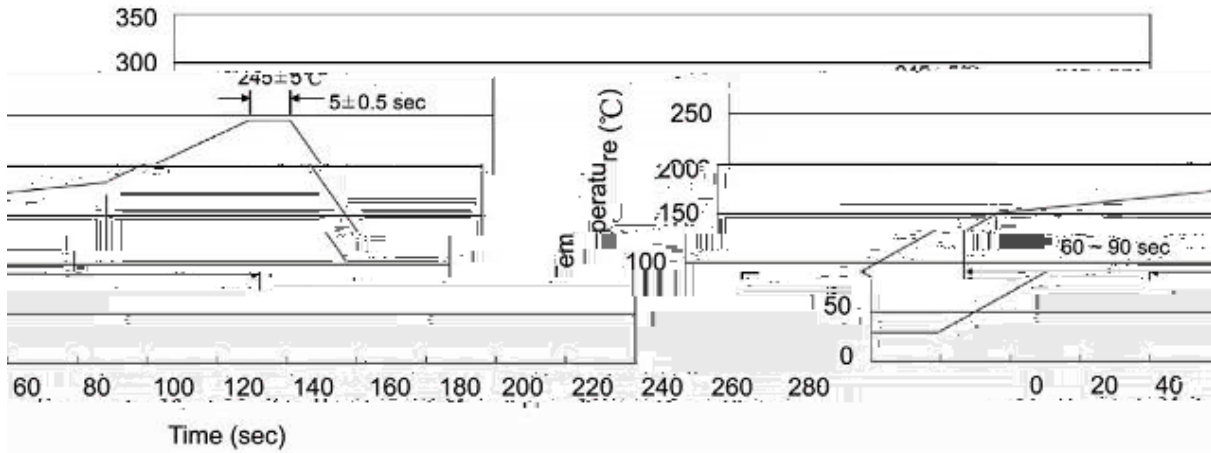
15T50

Product Type Code.

****:

Lot No. Code, code change with Lot No.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|----------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		

/ Notices